

Information note

N° 023/22

Dear customer,

With this Infineon Technologies AG information note, we would like to inform you about the following

Change of wafer backside processing from Xintec Inc., Taoyuan City, Taiwan to Phoenix Silicon International Corporation, Hsin Chu, Taiwan



On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

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► **Products affected**

Please refer to attached affected product list
 “INF_023-22_[customer-no].pdf”

► **Detailed change information**

Subject Change of wafer backside processing from Xintec Inc., Taoyuan City, Taiwan to Phoenix Silicon International Corporation, Hsin Chu, Taiwan for certain FET wafers. Wafer front side processing site and wafer probe site after backside processing are not changed.

Reason The wafer backside processing of the affected products will be transferred to Phoenix Silicon International Corporation, Hsin Chu, Taiwan according to the global Infineon production strategy.

Description

Wafer background and backmetal

<u>Old</u>	<u>New</u>
<ul style="list-style-type: none"> Xintec Inc., Taoyuan City, Taiwan 	<ul style="list-style-type: none"> Phoenix Silicon International Corporation, Hsin Chu, Taiwan

► **Product identification**

Traceability assured via internal part tracking.

► **Impact of change**

No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function.

► **Attachments**

2_cip02322 Qualification report

► **Intended start of delivery**

2022-07-01

If you have any questions, please do not hesitate to contact your local sales office.

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Change of wafer backside processing from Xintec Inc., Taoyuan City, Taiwan to
Phoenix Silicon International Corporation, Hsin Chu, Taiwan



Affected products sold to DIGI-KEY (4002348)

Sales name	SP number	OPN	Package	Customer part number
IRSM005-301MH	SP001541136	IRSM005-301MH	QFN 7X8 27L	IRSM005-301MH
IRSM505-025PA	SP001544090	IRSM505-025PA	SOP23	IRSM505-025PA
IRSM505-035PA	SP001546664	IRSM505-035PA	SOP23	IRSM505-035PA
IRSM505-055DA	SP001549868	IRSM505-055DA	DIP23	IRSM505-055DA
IRSM505-055PA	SP001544082	IRSM505-055PA	SOP23	IRSM505-055PA
IRSM505-065DA	SP001549108	IRSM505-065DA	DIP23	IRSM505-065DA
IRSM505-065PATR	SP001547086	IRSM505-065PATR	SOP23	IRSM505-065PATR
IRSM807-105MH	SP001543516	IRSM807-105MH	QFN 8X9 31L	IRSM807-105MH
IRSM808-105MH	SP001549046	IRSM808-105MH	QFN 8X9 31L	IRSM808-105MH
IRSM808-105MHTR	SP001549028	IRSM808-105MHTR	QFN 8X9 31L	IRSM808-105MHTR
IRSM808-204MH	SP001541016	IRSM808-204MH	QFN 9X8 31L	IRSM808-204MH
IRSM836-024MA	SP001541026	IRSM836-024MA	QFN 12X12 36L	IRSM836-024MA
IRSM836-025MA	SP001546868	IRSM836-025MA	QFN 12X12 36L	IRSM836-025MA
IRSM836-035MA	SP001539604	IRSM836-035MA	QFN 12X12 36L	IRSM836-035MA
IRSM836-035MB	SP001544304	IRSM836-035MB	QFN 12X12 27L	IRSM836-035MB
IRSM836-044MA	SP001543350	IRSM836-044MA	QFN 12X12 36L	IRSM836-044MA
IRSM836-045MA	SP001547052	IRSM836-045MA	QFN 12X12 37L	IRSM836-045MA
IRSM836-084MA	SP001546858	IRSM836-084MA	QFN 12X12 36L	IRSM836-084MA